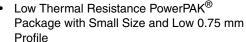




# P-Channel 20 V (D-S) MOSFET

| PRODU               | CT SUMMARY                           |                    |                       |
|---------------------|--------------------------------------|--------------------|-----------------------|
| V <sub>DS</sub> (V) | $R_{DS(on)}\left(\Omega\right)$ Max. | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |
|                     | 0.0036 at V <sub>GS</sub> = - 10 V   | - 40 <sup>e</sup>  |                       |
| - 20                | 0.0048 at V <sub>GS</sub> = - 4.5 V  | - 40 <sup>e</sup>  | 72 nC                 |
|                     | 0.0090 at V <sub>GS</sub> = - 2.5 V  | - 40 <sup>e</sup>  |                       |







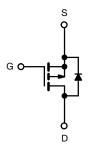
100 % R<sub>g</sub> and UIS Tested

Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

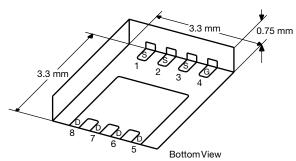
**FEATURES** 

- Smart Phones, Tablet PCs, Mobile Computing
  - Battery Switch
  - Load Switch



P-Channel MOSFET

## PowerPAK 1212-8S



Ordering Information: Si7655ADN-T1-GE3 (Lead (Pb)-free and Halogen-free)

| Parameter  |                           | Symbol                            | Limit                | Unit |  |
|--|---------------------------|-----------------------------------|----------------------|------|--|
| Drain-Source Voltage   |                           | V <sub>DS</sub>                   | - 20                 | V    |  |
| Gate-Source Voltage  |                           | V <sub>GS</sub>                   | ± 12                 |      |  |
|  | T <sub>C</sub> = 25 °C    |                                   | - 40 <sup>e</sup>    |      |  |
| Continuous Drain Current (T = 150 °C)                        | T <sub>C</sub> = 70 °C    |                                   | - 40 <sup>e</sup>    |      |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)           | T <sub>A</sub> = 25 °C    | - I <sub>D</sub>                  | - 31 <sup>a, b</sup> |      |  |
|  | T <sub>A</sub> = 70 °C    |                                   | - 25 <sup>a, b</sup> |      |  |
| Pulsed Drain Current (t = 300 μs)                            |                           | I <sub>DM</sub>                   | - 100                | A    |  |
| Continuous Course Durin Biodo Current                        | T <sub>C</sub> = 25 °C    | I-                                | - 40 <sup>e</sup>    |      |  |
| Continuous Source-Drain Diode Current                        | T <sub>A</sub> = 25 °C    | - Is                              | - 4 <sup>a, b</sup>  |      |  |
| Avalanche Current  | T <sub>C</sub> = 25 °C    | I <sub>AS</sub>                   | - 20                 |      |  |
| Single-Pulse Avalanche Energy                                | L = 0.111111              | E <sub>AS</sub>                   | 20                   | mJ   |  |
|  | T <sub>C</sub> = 70 °C 36 |                                   | 57                   |      |  |
| Maximum Power Dissipation                                    |                           | w                                 |                      |      |  |
| Maximum Fower Dissipation                                    | T <sub>A</sub> = 25 °C    | U U                               | 4.8 <sup>a, b</sup>  | VV   |  |
|  | T <sub>A</sub> = 70 °C    |                                   | 3 <sup>a, b</sup>    |      |  |
| Operating Junction and Storage Temperature Range             |                           | T <sub>J</sub> , T <sub>stg</sub> | - 50 to 150          | °C   |  |
| Soldering Recommendations (Peak Temperature) <sup>c, d</sup> |                           |                                   | 260                  |      |  |

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s
- c. See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- e. Package limited.

# Si7655ADN

# Vishay Siliconix



| THERMAL RESISTANCE RATIN                    | IGS          |                   |         |         |      |
|---|--------------|-------------------|---------|---------|------|
| Parameter                                   |              | Symbol            | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient <sup>a, b</sup> | t ≤ 10 s     | R <sub>thJA</sub> | 21      | 26      | °C/W |
| Maximum Junction-to-Case (Drain)            | Steady State | R <sub>thJC</sub> | 1.7     | 2.2     | C/VV |

Notes:

a.Surface mounted on 1" x 1" FR4 board. b.Maximum under steady state conditions is 63 °C/W.

| Parameter                                     | Symbol                  | Test Conditions   | Min.  | Тур.   | Max.              | Unit    |
|---|-------------------------|---|-------|--------|-------------------|---------|
| Static  |                         |   |       |        |                   |         |
| Drain-Source Breakdown Voltage                | $V_{DS}$                | $V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$                                     | - 20  |        |                   | V       |
| V <sub>DS</sub> Temperature Coefficient       | $\Delta V_{DS}/T_{J}$   | I - 250 uA  |       | - 12   |                   | mV/     |
| V <sub>GS(th)</sub> Temperature Coefficient   | $\Delta V_{GS(th)}/T_J$ | I <sub>D</sub> = - 250 μA   |       | 2.6    |                   | °C      |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>     | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$   | - 0.5 |        | - 1.1             | V       |
| Gate-Source Leakage                           | I <sub>GSS</sub>        | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$                                   |       |        | ± 100             | nA      |
| Zoro Coto Voltago Drain Current               | 1                       | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V                                     |       |        | - 1               |         |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>        | V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C             |       |        | - 10              | μΑ      |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>      | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$                                   | - 20  |        |                   | Α       |
|   | , ,                     | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 20 A                                   |       | 0.0030 | 0.0036            | Ω       |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>     | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 15 A                                  |       | 0.0039 | 0.0048            |         |
|   | , , ,                   | V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 10 A                                  |       | 0.0062 | 0.0090            |         |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>         | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 20 A                                   |       | 90     |                   | S       |
| Dynamic <sup>b</sup>                          |                         | -   |       |        |                   |         |
| Input Capacitance                             | C <sub>iss</sub>        |   |       | 6600   |                   | pF      |
| Output Capacitance                            | C <sub>oss</sub>        | V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                          |       | 890    |                   |         |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>        |   |       | 930    |                   |         |
| Total Gate Charge                             | Q <sub>g</sub>          | V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 20 A         |       | 150    | 225               | nC      |
|   |                         |   |       | 72     | 110               |         |
| Gate-Source Charge                            |                         | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -20 \text{ A}$            |       | 12     |                   |         |
| Gate-Drain Charge                             | $Q_{gd}$                |   |       | 19     |                   |         |
| Gate Resistance                               | $R_q$                   | f = 1 MHz   | 0.5   | 2.6    | 5.2               | Ω       |
| Turn-On Delay Time                            | t <sub>d(on)</sub>      |   |       | 45     | 90                |         |
| Rise Time                                     | t <sub>r</sub>          | $V_{DD} = -10 \text{ V}, R_{L} = 1 \Omega$  |       | 45     | 90                |         |
| Turn-Off DelayTime                            | t <sub>d(off)</sub>     | $I_D \cong$ - 10 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$                         |       | 100    | 200               |         |
| Fall Time                                     | t <sub>f</sub>          | _   |       | 35     | 70                |         |
| Turn-On Delay Time                            | t <sub>d(on)</sub>      |   |       | 13     | 25                | ns<br>- |
| Rise Time                                     | t <sub>r</sub>          | $V_{DD} = -10 \text{ V}, R_1 = 1 \Omega$  |       | 10     | 20                |         |
| Turn-Off DelayTime                            | t <sub>d(off)</sub>     | $I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$                  |       | 110    | 220               |         |
| Fall Time                                     | t <sub>f</sub>          | Ţ   |       | 25     | 50                |         |
| <b>Drain-Source Body Diode Characterist</b>   | ics                     |   |       |        |                   |         |
| Continuous Source-Drain Diode Current         | I <sub>S</sub>          | T <sub>C</sub> = 25 °C  |       |        | - 40 <sup>c</sup> | _       |
| Pulse Diode Forward Current <sup>a</sup>      | I <sub>SM</sub>         |   |       |        | - 100             | A       |
| Body Diode Voltage                            | V <sub>SD</sub>         | I <sub>F</sub> = - 10 A   |       | - 0.75 | - 1.2             | V       |
| Body Diode Reverse Recovery Time              |                         |   |       | 30     | 60                | ns      |
| Body Diode Reverse Recovery Charge            | Q <sub>rr</sub>         | 1 40 A 41/44 400 A/22 T 05 00   |       | 17     | 26                | nC      |
| Reverse Recovery Fall Time                    | t <sub>a</sub>          | $I_F = -10 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$ |       | 15     |                   | ns      |
| Reverse Recovery Rise Time                    | t <sub>b</sub>          |   |       | 15     |                   |         |

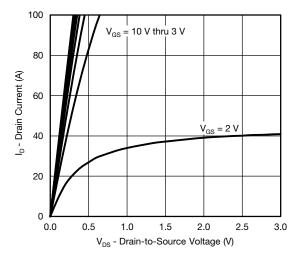
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.
- c. Package limited.

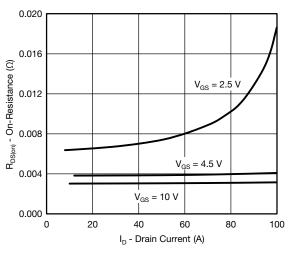
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



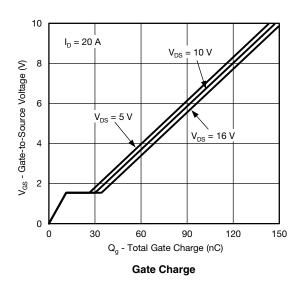
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

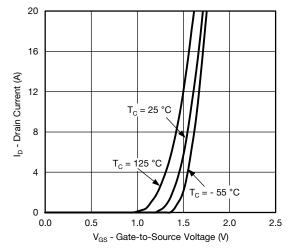


### **Output Characteristics**

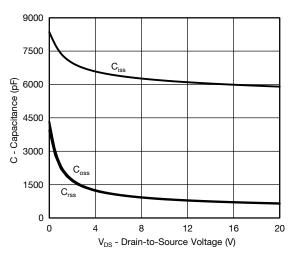


On-Resistance vs. Drain Current and Gate Voltage

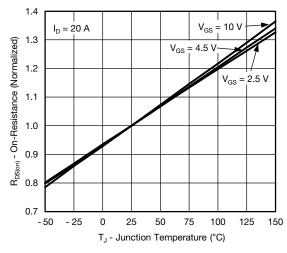




**Transfer Characteristics** 



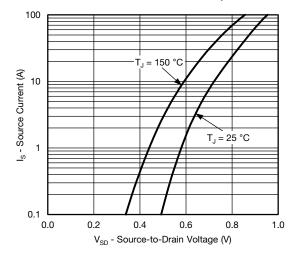
Capacitance

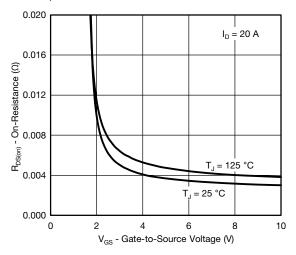


On-Resistance vs. Junction Temperature

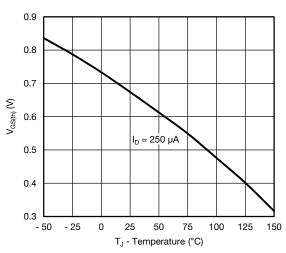
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

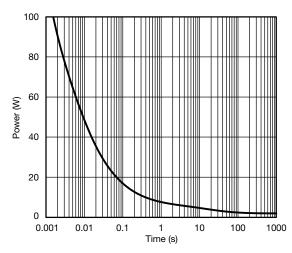




### Source-Drain Diode Forward Voltage

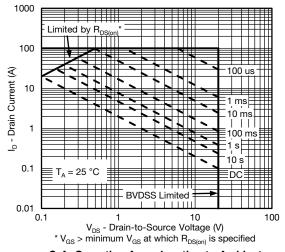


On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

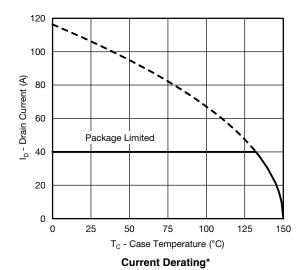
Single Pulse Power, Junction-to-Ambient

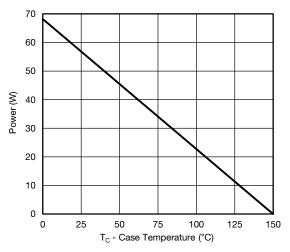


Safe Operating Area, Junction-to-Ambient

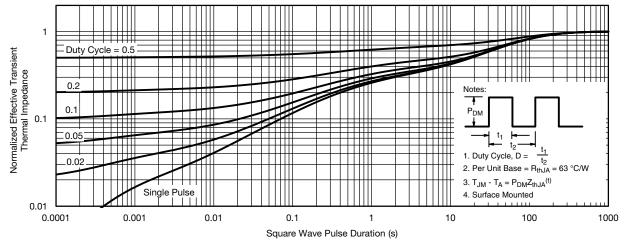


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Power, Junction-to-Case

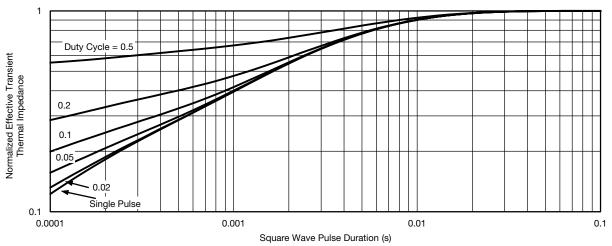


Normalized Thermal Transient Impedance, Junction-to-Ambient

 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150  $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

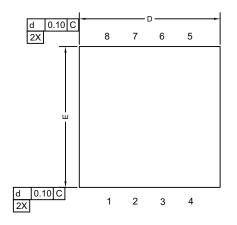


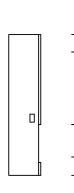
Normalized Thermal Transient Impedance, Junction-to-Case

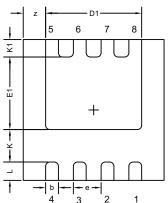
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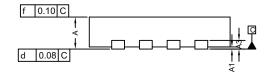


# Case Outline for PowerPAK® 1212-8S









| DIM. | MILLIMETERS |           |      | INCHES    |           |       |  |  |
|------|-------------|-----------|------|-----------|-----------|-------|--|--|
|      | MIN.        | NOM.      | MAX. | MIN.      | NOM.      | MAX.  |  |  |
| Α    | 0.67        | 0.75      | 0.83 | 0.027     | 0.030     | 0.033 |  |  |
| A1   | 0           | -         | 0.05 | 0         | -         | 0.002 |  |  |
| А3   |             | 0.20 REF  |      |           | 0.008 REF |       |  |  |
| b    |             | 0.30 BSC  |      | 0.012 BSC |           |       |  |  |
| D    |             | 3.30 BSC  |      | 0.130 BSC |           |       |  |  |
| D1   | 2.15        | 2.25      | 2.35 | 0.084     | 0.088     | 0.092 |  |  |
| E    |             | 3.30 BSC  |      | 0.130 BSC |           |       |  |  |
| E1   | 1.60        | 1.70      | 1.80 | 0.063     | 0.067     | 0.071 |  |  |
| е    |             | 0.65 BSC  |      | 0.026 BSC |           |       |  |  |
| K    |             | 0.76 TYP  |      | 0.030 TYP |           |       |  |  |
| K1   |             | 0.41 TYP  |      | 0.016 TYP |           |       |  |  |
| L    |             | 0.43 BSC  |      | 0.017 BSC |           |       |  |  |
| Z    |             | 0.525 TYP |      | 0.021 TYP |           |       |  |  |

## DWG: 6008

### Note

• Millimeters will govern.



## RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Vishay

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